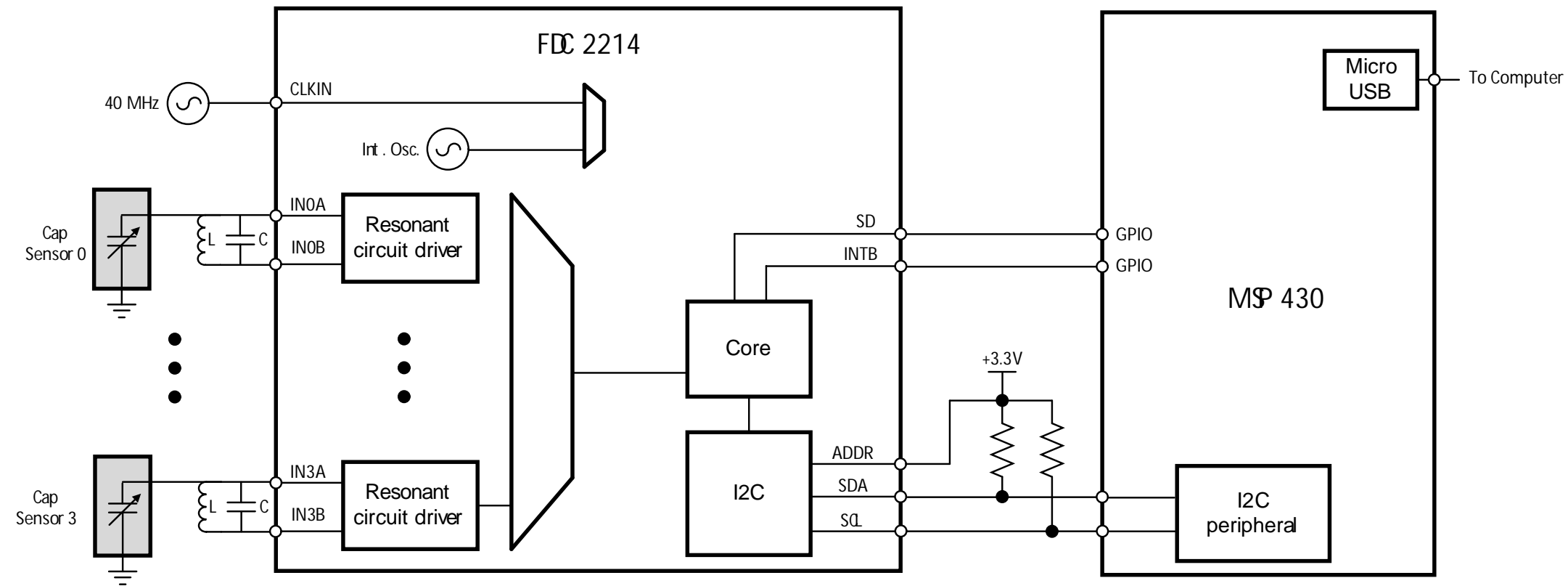


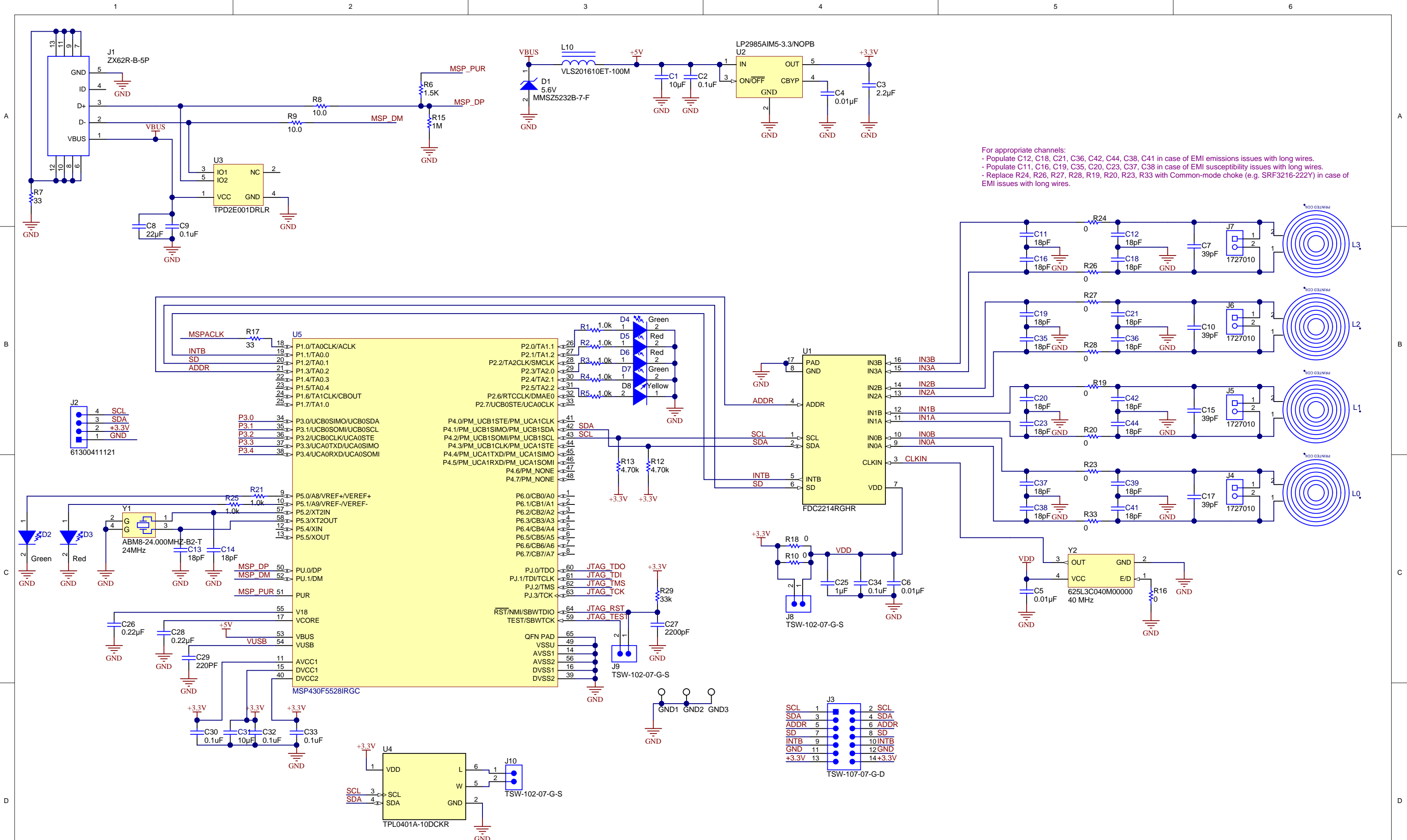
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



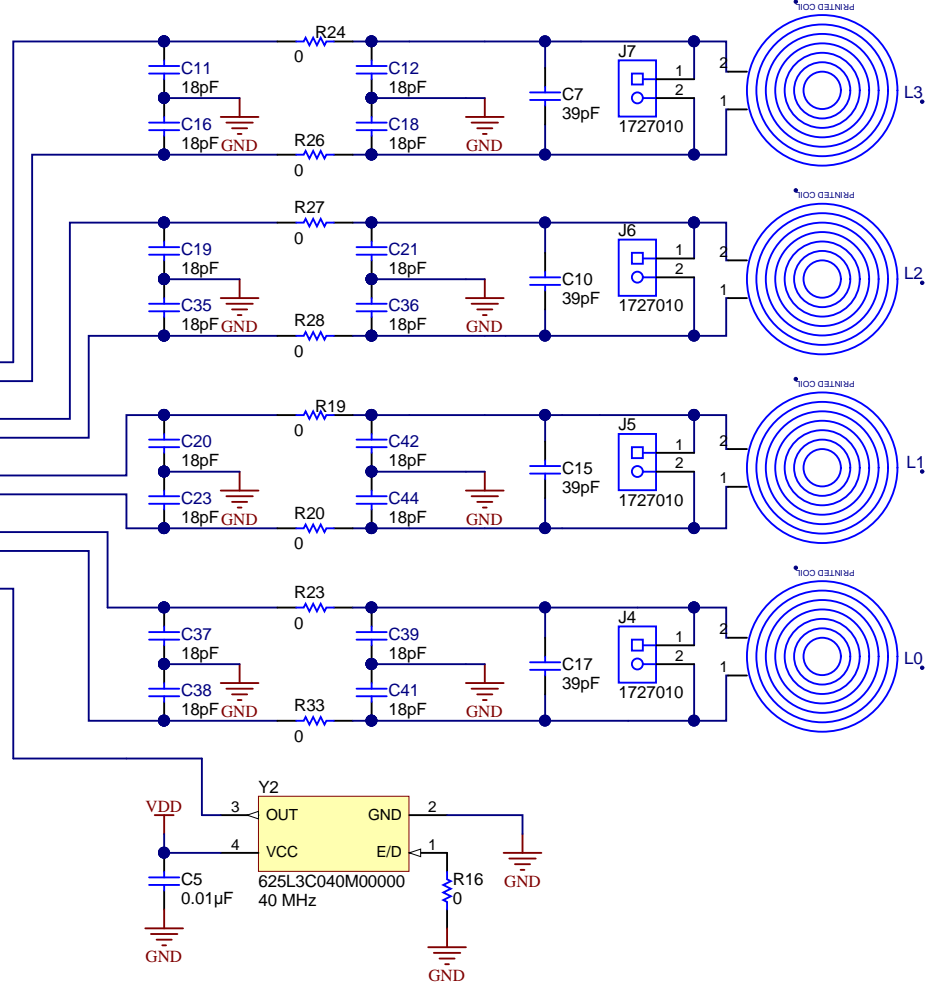
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TID #: TIDA-01465	Project Title: Frost and ice detection		
Number: TIDA-01465	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By: Richard Wang	File: TIDA-01465_CoverSheet_SchDoc	Size: B	
Engineer: Richard Wang	Contact: http://www.ti.com/support		



For appropriate channels:
 - Populate C12, C18, C21, C36, C42, C44, C38, C41 in case of EMI emissions issues with long wires.
 - Populate C11, C16, C19, C35, C20, C23, C37, C38 in case of EMI susceptibility issues with long wires.
 - Replace R24, R26, R27, R28, R19, R20, R23, R33 with Common-mode choke (e.g. SRF3216-222Y) in case of EMI issues with long wires.



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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 2017/8/28
TID #: TIDA-01465	Project Title: Frost and ice detection	
Number: TIDA-01465	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: Richard Wang	File: TIDA-01465_Main.SchDoc	Size: B
Engineer: Richard Wang	Contact: http://www.ti.com/support	





PCB Number: TIDA-01465
PCB Rev: E1

PCB LOGO
ESD Susceptible

PCB LOGO
Pb-Free Symbol

PCB LOGO
CAUTION. READ USER GUIDE BEFORE USE

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 2017/8/4
TID #: TIDA-01465	Project Title: Frost and ice detection	
Number: TIDA-01465	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: TIDA-01465_Hardware.SchDoc	Size: B
Engineer: Richard Wang	Contact: http://www.ti.com/support	



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